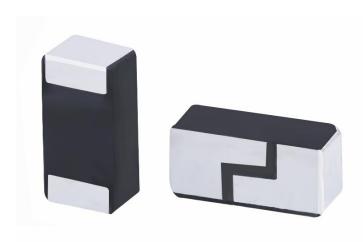


Series: Chip Antenna

#### **TECHNICAL DATA SHEET**

Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C



#### Features:

2400-2483.5MHz

Size: 3.2 x 1.6 x 1.1mm

• Efficiency: 68 %

Gain: 1.3 dBi

Polarization: Linear

Power Handling: 5W

RoHS Compliant

Moisture Sensitivity Level MSL1

## **Applications:**

Bluetooth, BLE, Zigbee, WiFi

· 2.4GHz ISM band radios

All dimensions are in mm / inches

Issue: 1946

In the effort to improve our products, we reserve the right to make changes judged to be necessary. CONFIDENTIAL AND PROPRIETARY INFORMATION

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Europe Headquarters Pulse GmbH & Do, KG Zeppelinstrasse 15 Herrenberg, Germany Tel: 49 7032 7806 0 Pulse (Suzhou) Wireless Products Co, Inc. 99 Huo Ju Road(#29 Bldg,4<sup>th</sup> Phase Suzhou New District Jiangsu Province, Suzhou 215009 PR China Tel: 86 512 6807 9998



Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

## Series: Chip Antenna

ELECTRICAL SPECIFICATIONS		
Frequency	2400-2483.5MHz	
Nominal Impedance	50 Ω	
Return Loss	-8dB	
Radiation Pattern	Omni	
Gain	1.3dBi	
Efficiency	68%	
Polarization	Linear	
Power Withstanding	5W	

#### **MECHANICAL SPECIFICATIONS**

Weight	0.03 g
Overall Length	3.2 [0.126] MM [INCHES]
Over all width	1.6 [0.063] MM [INCHES]
Over all thickness	1.1 [0.043] MM [INCHES]
MSL (Moisture Sensitivity Level)	1

#### **ENVIRONMENTAL SPECIFICATIONS**

Operating Temperature	-40~+85° C
Storage Temperature	-40~+85° C
RoHS Compliant	Yes

(\*) All RF parameters measured on 80\*37mm PCB with 4\*6.25mm clearance in free space. No matching component used.



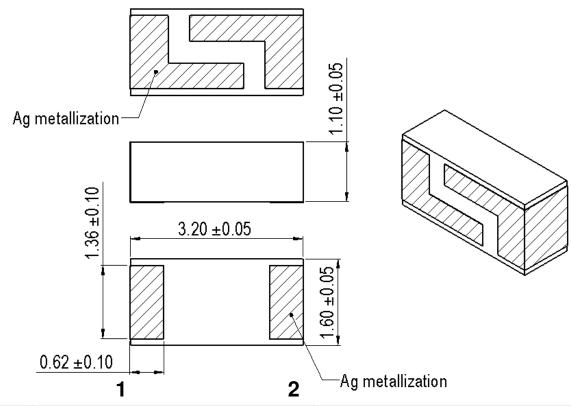


Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

## Series: Chip Antenna

#### **MECHANICAL DRAWING**



No.	Terminal Name	Terminal Dimensions
1	Feed /GND	0.62 x 1.36 mm
2	Feed /GND	0.62 x 1.36 mm
Antenna is symmetrical, either one of pads 1 or 2 can be used as feed terminal		

Note: This type of antenna is called loaded PIFA. One pad (on the bottom of the ceramic chip antenna) that feedline and GND are connected is a basic PIFA antenna structure. And, another pad on the other side that only GND is connected is for capacitive loading. Loaded capacitive value is optimized by the gap distance between two pads on the top surface. In PIFA, there is short mechanism usually in proximity to feed. This RF shorting affects impedance and current distribution mechanism of antenna. The actual antenna top face can seem to be mirrored, however it can be used same as the non-mirrored version. Please follow the design recommendation specified in this data sheet for either case.



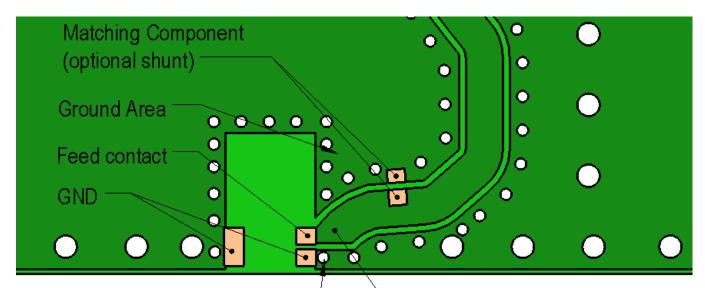
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

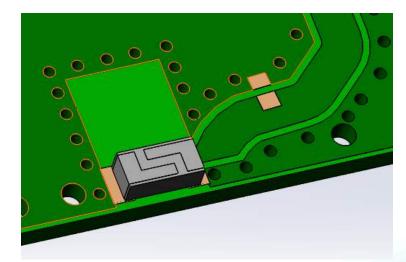
#### MECHANICAL DRAWING AND TERMINAL CONFIGURATION

### Ground cleared under antenna, clearance area 4 mm x 6.25mm



Ground Via Hole Ground area should be surround with ground via holes

Feed line 500hm Any type of 50 Ohm feed line can be used, inner layers on feed line area need to designed to give 50 Ohm characteristics to feed line





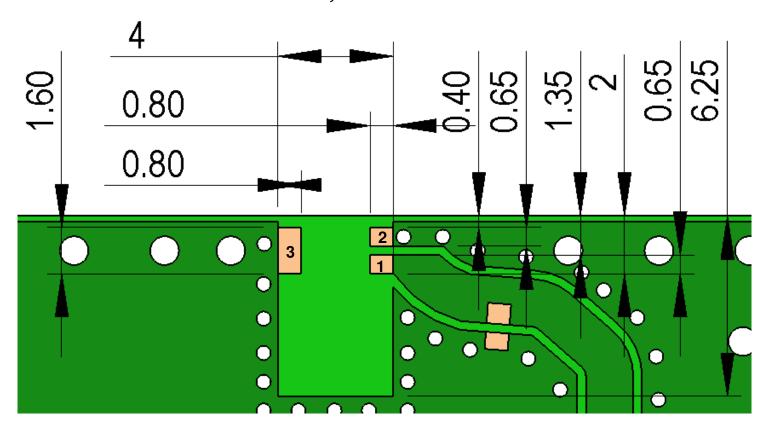
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

#### **MECHANICAL DRAWING AND TERMINAL CONFIGURATION**

Recommended Antenna Pad Dimensions on PCB Layout (top surface) Ground cleared under antenna, clearance area 4 mm x 6.25 mm



PCB contact pads		
No.	Terminal Name	Terminal Dimensions
1	Feed	0,80 x 0,65 mm
2	GND	0,80 x 0,65 mm
3	GND	0,80 x 1,60 mm



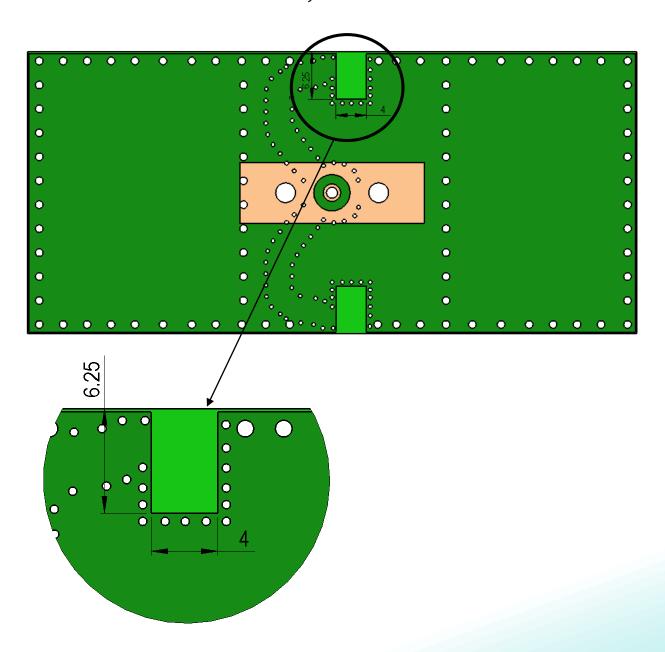
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

#### MECHANICAL DRAWING AND TERMINAL CONFIGURATION

Recommended Antenna Pad Dimensions on PCB Layout (bottom surface) Ground cleared under antenna, clearance area 4 mm x 6.25 mm









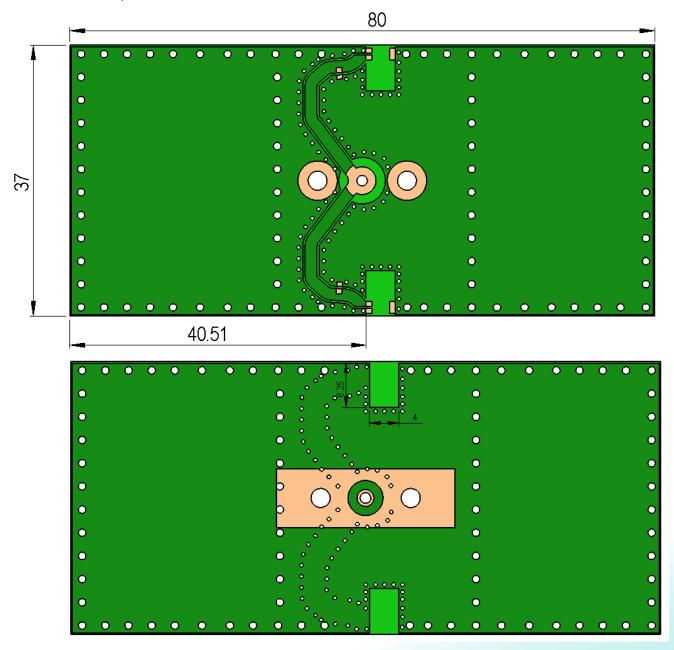
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

#### MECHANICAL DRAWING AND TERMINAL CONFIGURATION

Recommended test board layout for electrical characteristic measurement, test board outline size 80 x 37mm









Description: 2.4-2.4835GHz Ceramic SMT

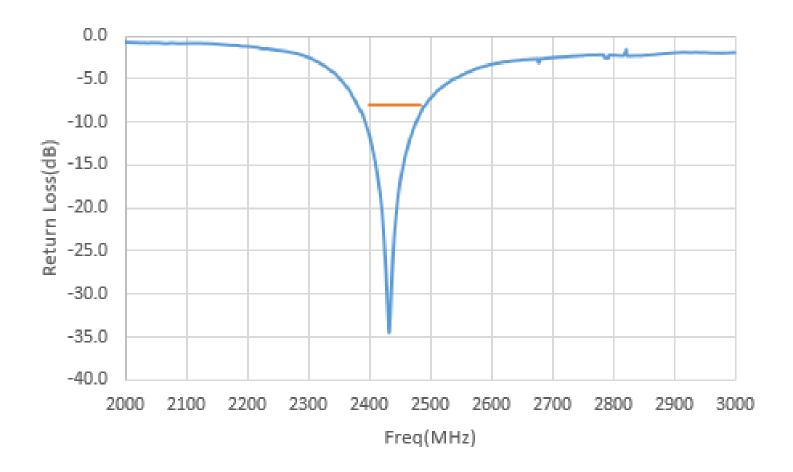
antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

## **Series: Chip Antenna**

#### **CHARTS**

#### Return loss



(\*) All RF parameters measured on 80\*37mm PCB with 4\*6.25mm clearance in free space. No matching component used.





Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

# **CHARTS** Efficiency(%) 80 70 60 50 Efficiency(%) 30 20 10

(\*) All RF parameters measured on 80\*37mm PCB with 4\*6.25mm clearance in free space. No matching component used.





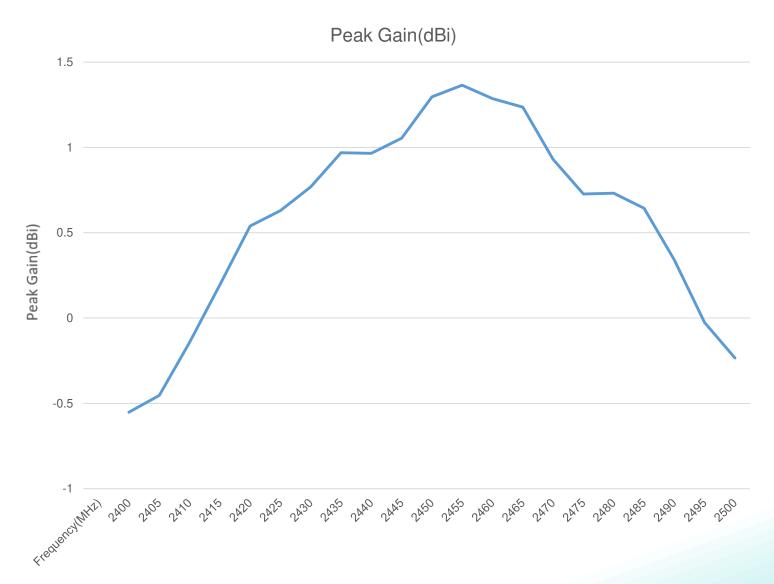
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

#### **CHARTS**

## Peak Gain(dBi)



(\*) All RF parameters measured on 80\*37mm PCB with 4\*6.25mm clearance in free space. No matching component used.





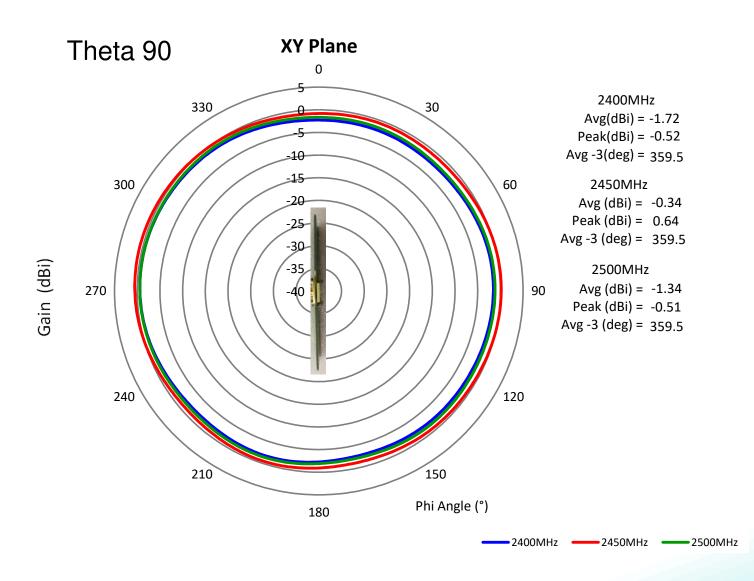
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

#### **CHARTS**

## Free Space Radiation Pattern



(\*) All RF parameters measured on 80\*37mm PCB with 4\*6.25mm clearance in free space. No matching component used.





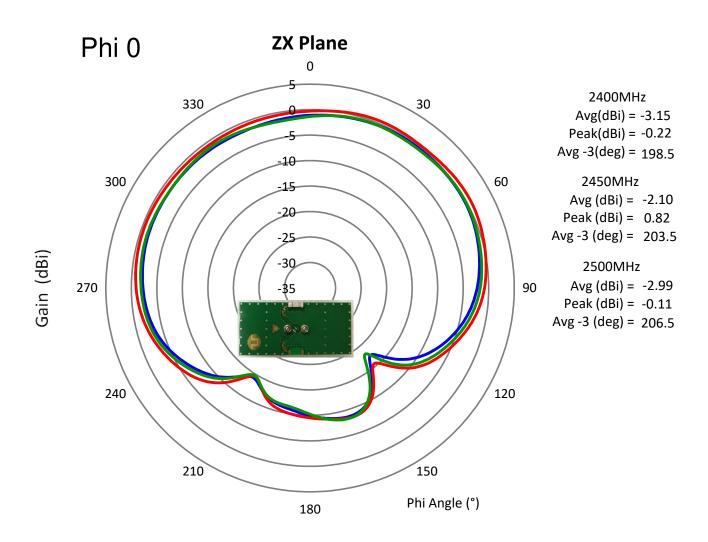
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

#### **CHARTS**

## Free Space Radiation Pattern



(\*) All RF parameters measured on 80\*37mm PCB with 4\*6.25mm clearance in free space. No matching component used.





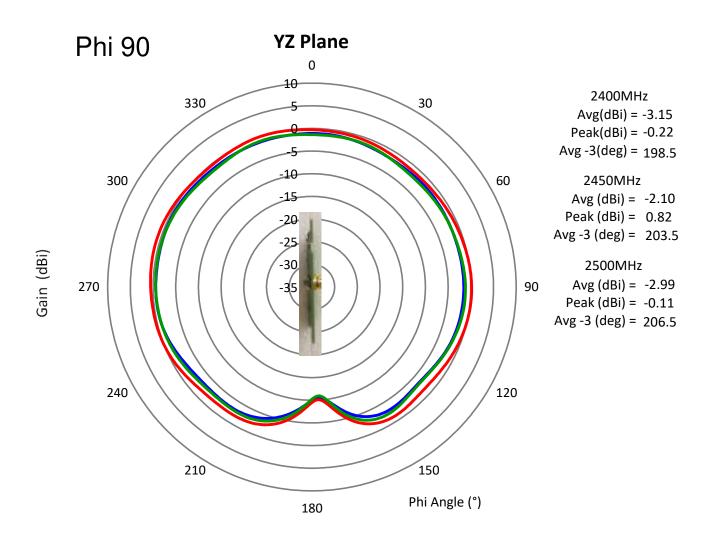
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

Series: Chip Antenna

#### **CHARTS**

## Free Space Radiation Pattern



(\*) All RF parameters measured on 80\*37mm PCB with 4\*6.25mm clearance in free space. No matching component used.



## Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

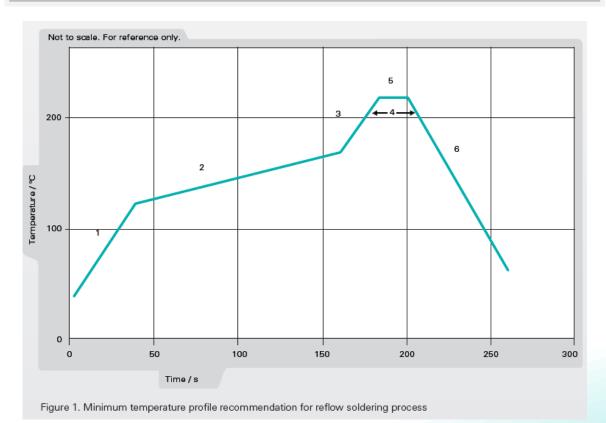
PART NUMBER: W3008C

## **Series: Chip Antenna**

#### **Recommendation for reflow soldering process**

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 ℃ for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s



Issue: 1946



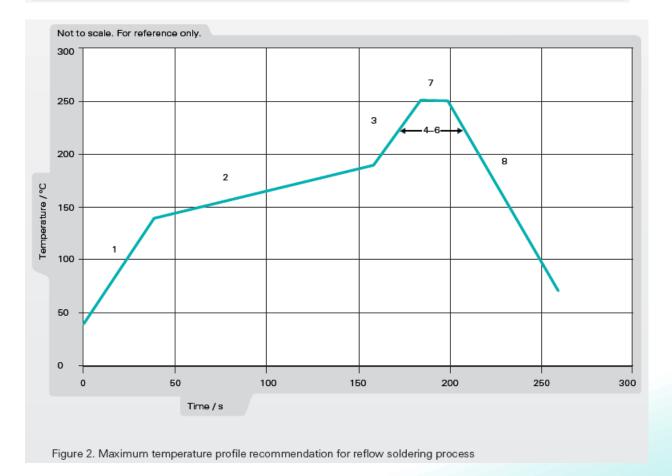
Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

**PART NUMBER: W3008C** 

## **Series: Chip Antenna**

## **Recommendation for reflow soldering process**

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s



Issue: 1946



Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

## **Series: Chip Antenna**

#### **PACKAGING-1**

3000pcs antennas per 7" reel

5pcs 7" reel per inner package box

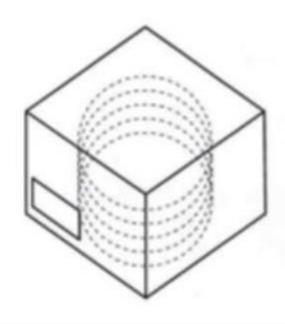
2pcs inner box per out box

Total 30000pcs antenna per out box

Out box size: 390mmx215mmx165mm







#### **LEVEL**

#### NOT MOISTURE SENSITIVE



These Devices do not require special storage conditions provided:

- They are maintained at conditions equal to or less than 30°C and 85% RH.
- They are solder reflowed at a peak body temperture which does not exceed 260°C.

Note: Level and body temperture defined by IPC/JEDEC J-STD-020



Description: 2.4-2.4835GHz Ceramic SMT antenna, 4x6.25mm keep out area

PART NUMBER: W3008C

## Series: Chip Antenna

#### **PACKAGING-2**

